

特点

- 芯片与底板电气绝缘，2500V交流电压
- 采用进口玻璃钝化芯片焊接，优良的温度特性进口和功率循环能力
- 体积小，重量轻

| | |
|-------------------|------------------|
| $I_{F(AV)}$ | 200A |
| V_{DRM}/V_{RRM} | 500-2500V |
| I_{TSM} | 8 KA |
| I^2t | 326 $10^3 a^2 s$ |

典型应用

- 变频器
- 交直流电机控制
- 各种整流电源

| 符号 | 参数 | 测试条件 | 结温 $T_J(°C)$ | 参数值 | | | 单位 |
|---------------|-----------|--|-----------------|------|----|-------|---------------------|
| | | | | 最小 | 典型 | 最大 | |
| $I_{F(AV)}$ | 正向平均电流 | 180° 正弦半波, 50HZ 单面散热, $T_C=100°C$ | 150 | | | 200 | A |
| $I_{F(RMS)}$ | 方均根电流 | | 150 | | | 314 | A |
| V_{RRM} | 反向重复峰值电压 | $V_{RRM} t_p=10ms$ $V_{RSM}=V_{RRM}+200V$ | 150 | 500 | | 2500 | V |
| I_{RRM} | 反向重复峰值电流 | $V_{RM}=V_{RRM}$ | 150 | | | 12 | mA |
| I_{FSM} | 正向不重复浪涌电流 | 10ms 底宽, 正弦半波 $V_R=0.6V_{RRM}$ | 150 | | | 8.00 | KA |
| I^2t | 浪涌电流平方时间积 | | | | | 326 | $A^{2S} \cdot 10^3$ |
| V_{FO} | 门槛电压 | | 150 | | | 0.75 | V |
| r_F | 斜率电阻 | | | | | 0.88 | mΩ |
| V_{FM} | 正向峰值电压 | $I_{FM}=600A$ | 25 | | | 1.20 | V |
| $R_{th(j-c)}$ | 热阻抗 (结至壳) | 180° 正弦波, 单面散热 | | | | 0.210 | °C/W |
| $R_{th(c-h)}$ | 热阻抗 (壳至散) | 180° 正弦波, 单面散热 | | | | 0.08 | °C/W |
| V_{iso} | 绝缘电压 | 50Hz, R.M.S, $t=1min, I_{iso}: 1mA(max)$ | | 2500 | | | V |
| F_M | 安装扭矩 (M5) | | | | | 6 | N-m |
| | 安装扭矩 (M6) | | | | | 6 | N-m |
| T_{stq} | 储存温度 | | | -40 | | 125 | °C |
| W_t | 质量 | | | | | | g |
| Outline | 外形 | | | | | | |

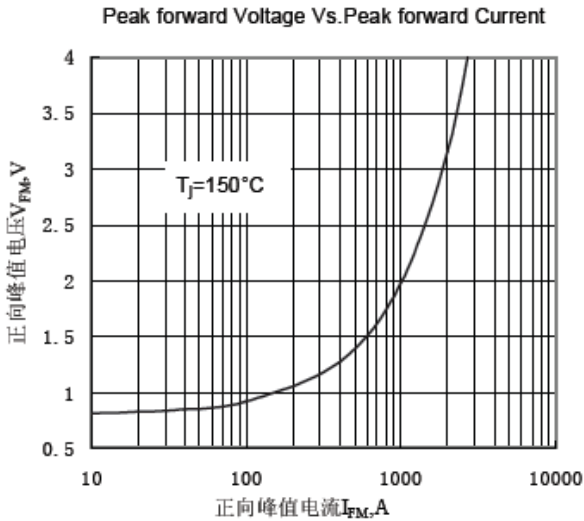


Fig.1 正向伏安特性曲线

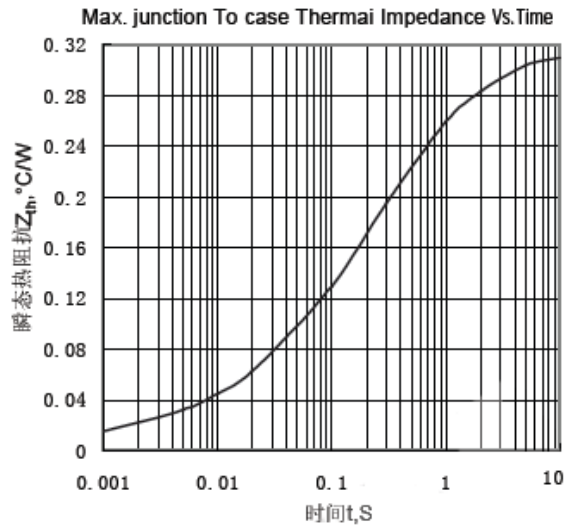


Fig.2 瞬态热阻抗曲线

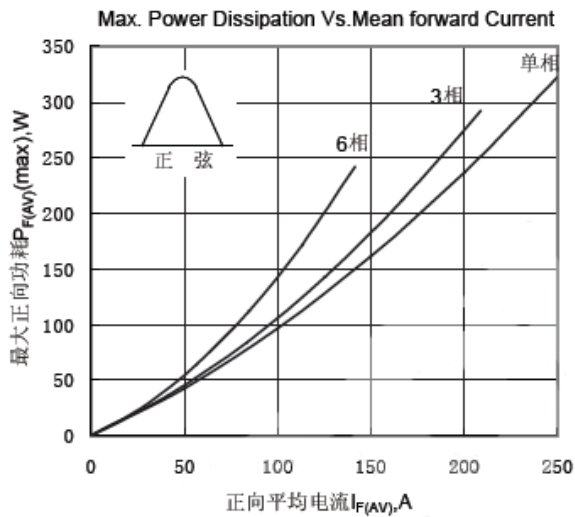


Fig.3 最大正向功耗与平均电流关系曲线

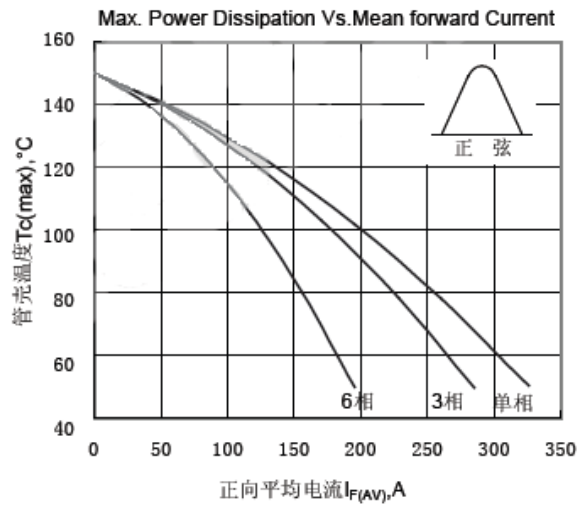


Fig.4 管壳温度与正向平均电流关系曲线

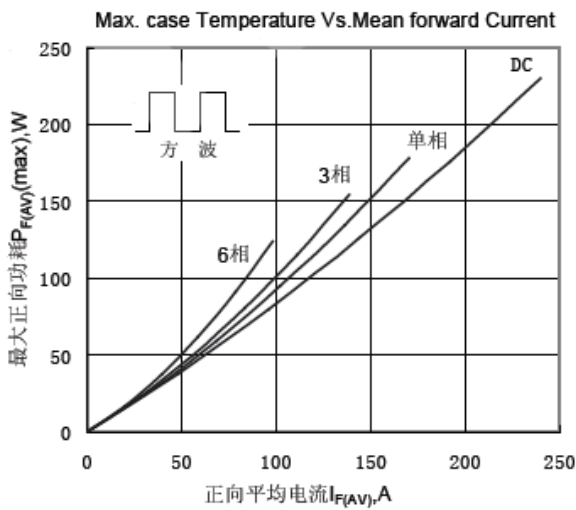


Fig.5 最大正向功耗与平均电流关系曲线

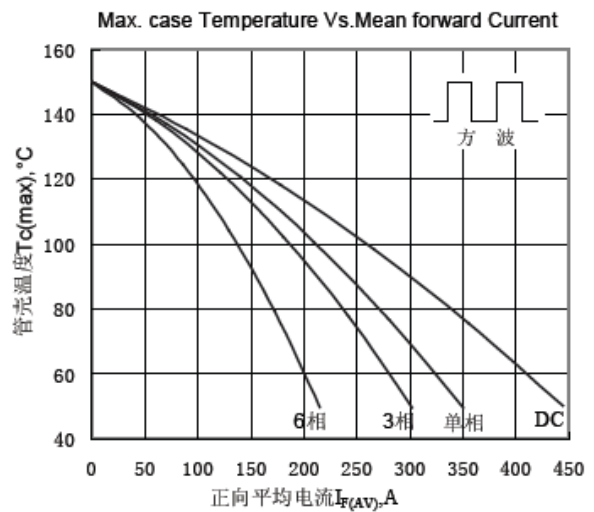


Fig.6 管壳温度与正向平均电流关系曲线

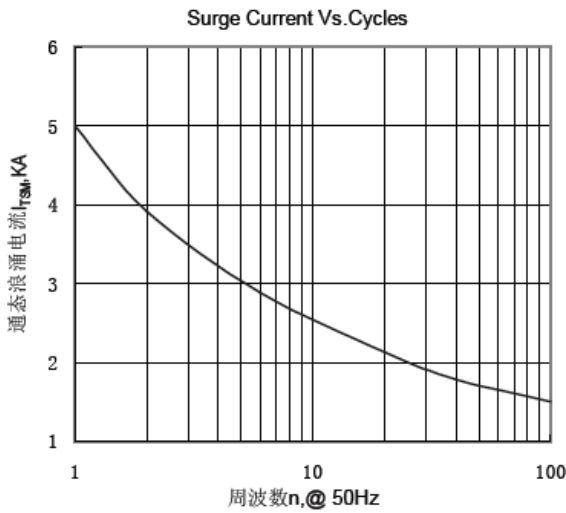


Fig.7 通态浪涌电流与周波数的关系曲线

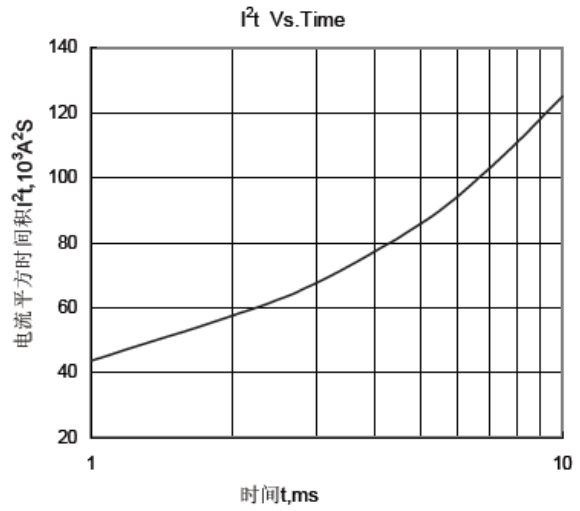


Fig.8 I^2t 特性曲线

外形图:

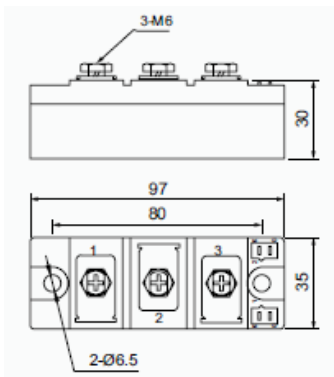


图 1

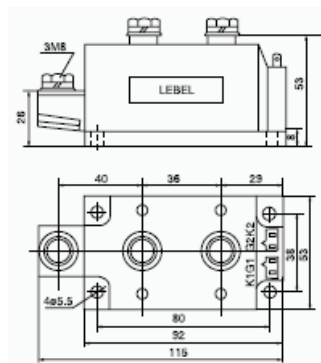


图 2

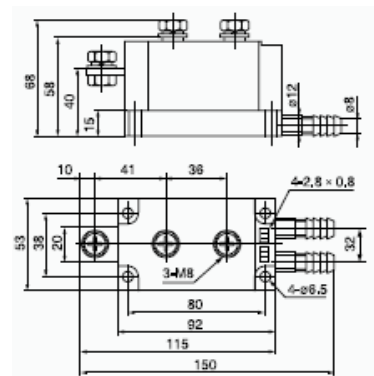


图 3

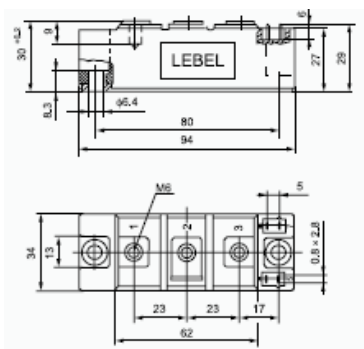


图 4

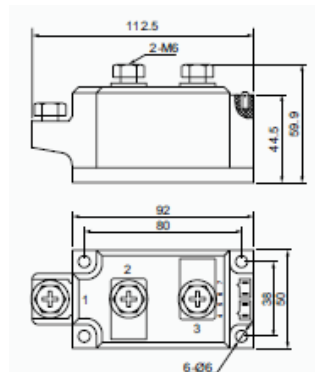


图 5

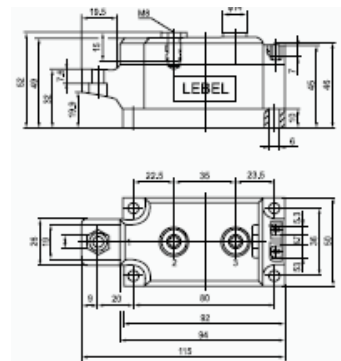


图 6

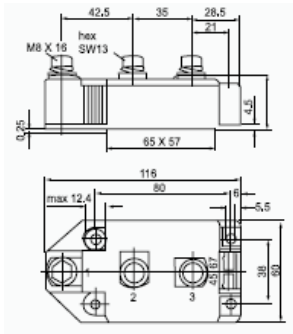


图 7

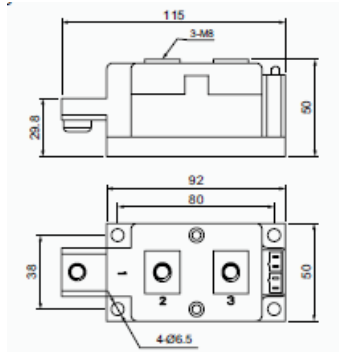


图 8

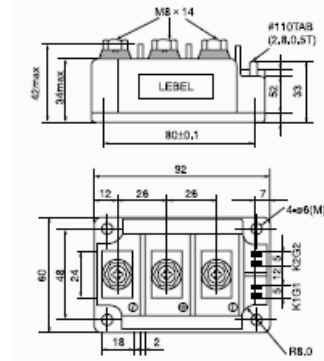


图 9

线路图:

